



UNIVERSITY OF
BIRMINGHAM

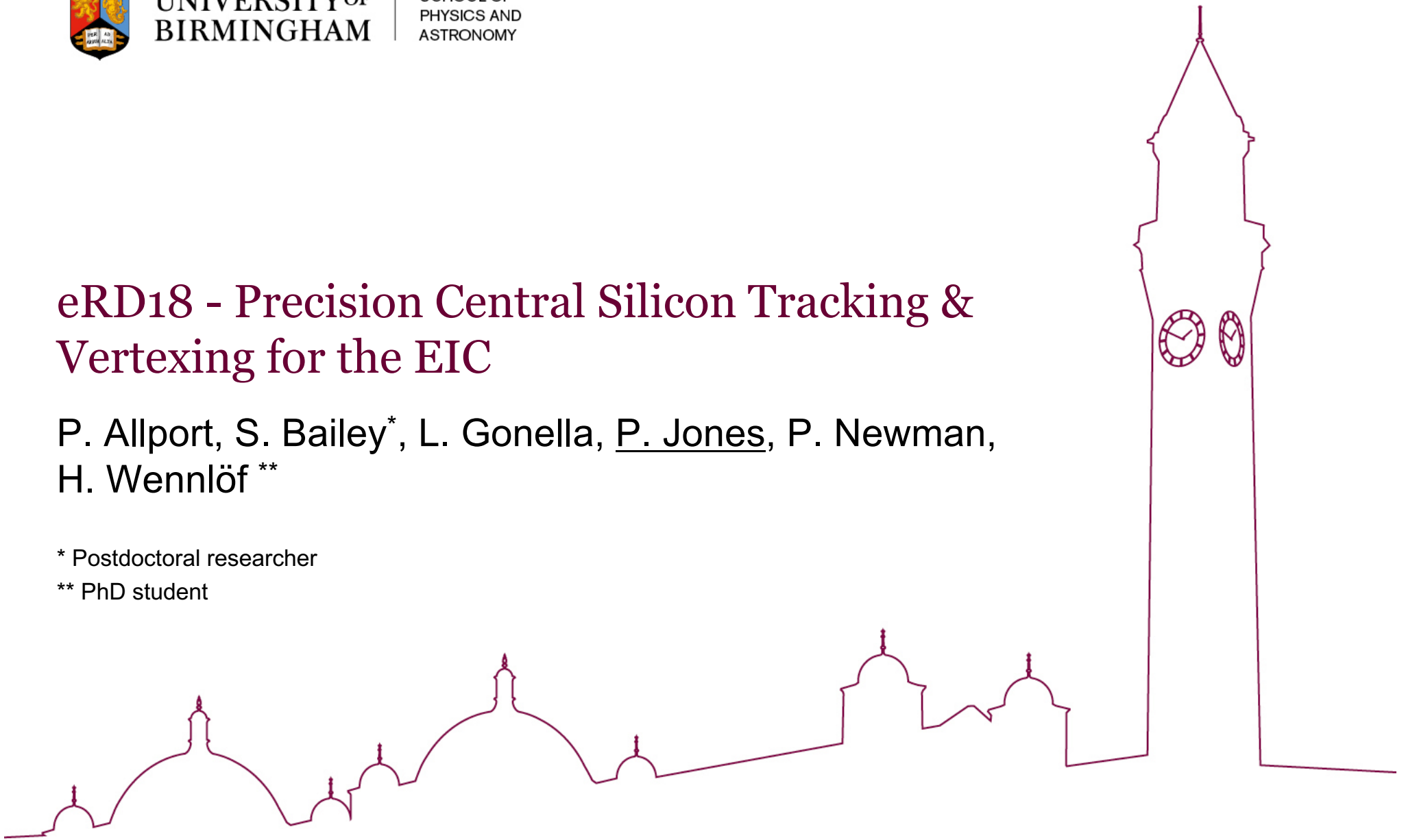
SCHOOL OF
PHYSICS AND
ASTRONOMY

eRD18 - Precision Central Silicon Tracking & Vertexing for the EIC

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H. Wennl f **

* Postdoctoral researcher

** PhD student



eRD18: Proposal

To develop a detailed concept for a central silicon vertex detector for a future EIC experiment, exploring the potential advantages of depleted MAPS (DMAPS) technologies

Physics motivation

Open heavy flavour decays – **high position resolution**

Precision tracking of high Q^2 scattered electrons – **low mass**

WP1: Sensor Development

Exploit on-going R&D in Birmingham into DMAPS
to investigate potential solutions for the EIC

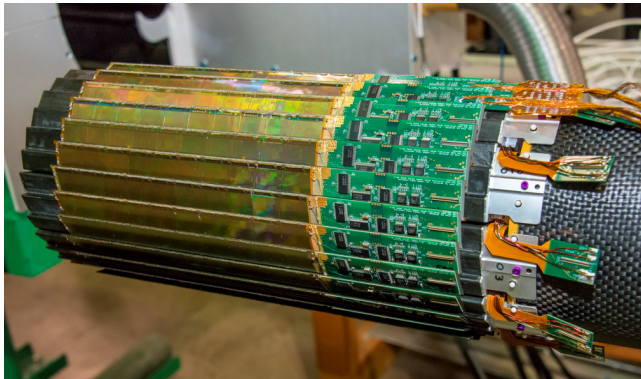
WP2: Silicon Detector Layout Investigations

Optimise the numbers of layers, layout and spatial resolution
to achieve the required tracking and vertex reconstruction performance



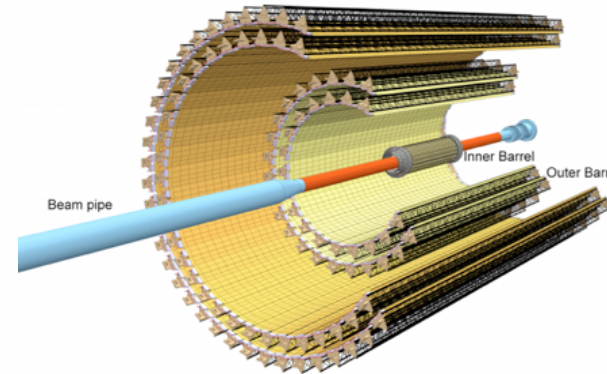
Background: State-of-the-art MAPS

STAR Heavy Flavour Tracker (HFT) at RHIC



MIMOSA (AMS 0.35 μm CMOS process)

ALICE Inner Tracking System (ITS) Upgrade at LHC

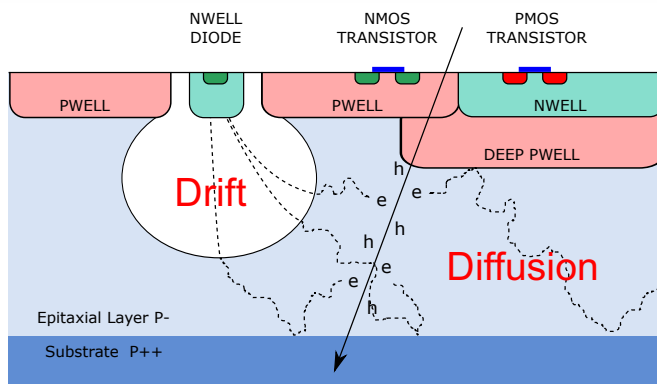


ALPIDE (TowerJazz 0.18 μm CMOS process)

- Key features of MAPS
 - Small pixel size (down to 20 μm x 20 μm)
 - Low power (< few hundred mW/cm²)
 - Low material budget ($\sim 0.3\%$ X_0 per layer)
 - Moderate radiation hardness ($\sim \text{Mrad}$, 10^{13} 1MeV $n_{\text{eq}}/\text{cm}^2$)

Background: State-of-the-art MAPS

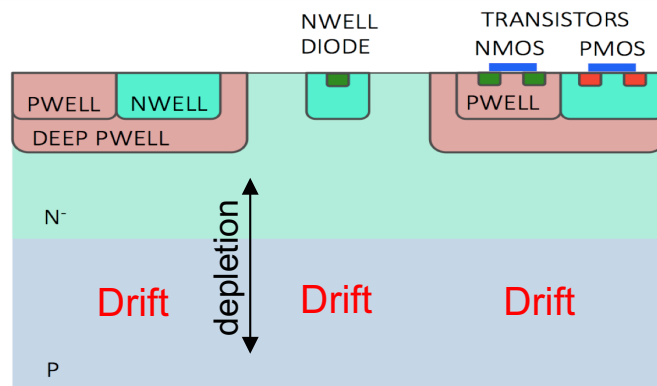
- Starting point is the ALICE ALPIDE sensor (MAPS)



ALPIDE sensor

- 0.18 μm CMOS *standard* TowerJazz (TJ) process
- $28 \times 28 \mu\text{m}^2$ pixel pitch
- Small collection electrode = low capacitance
- Partially depleted; charge collection *in part* by drift

- Future is fully depleted MAPS (DMAPS)



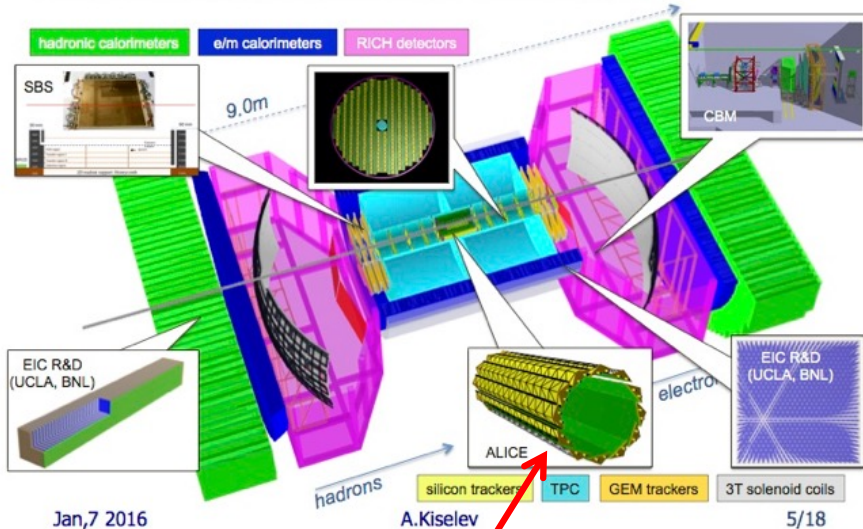
Example: TowerJazz modified process

- 0.18 μm CMOS *modified* TowerJazz (TJ) process
- Introduces additional planar junction
- Fully depleted sensor; charge collection by drift
- Faster, more complete charge collection
- Less charge sharing between pixels

Background: EIC Detector Concepts

BeAST detector layout

$-4 < \eta < 4$: Tracking & e/m Calorimetry (hermetic coverage)



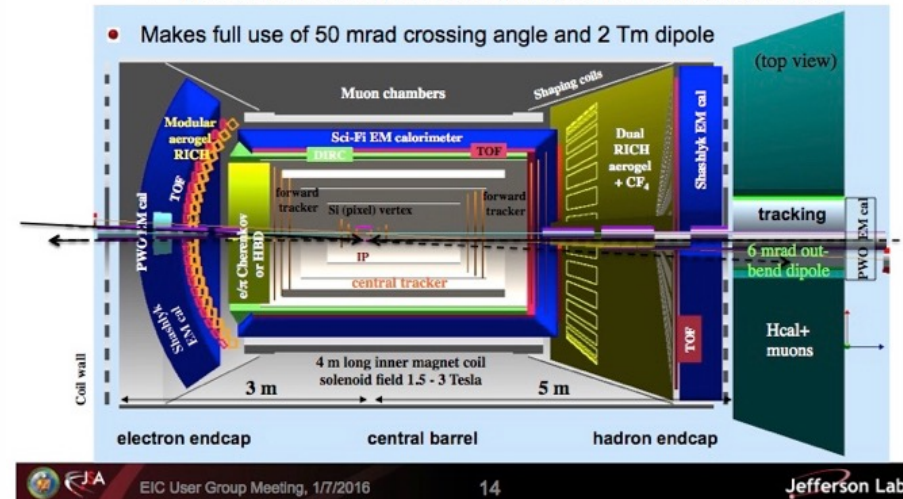
Alexander Kiselev

Based on **ALICE ITS** inner layer design

- Si vertex and tracker detectors in central and forward regions
- Seek high resolution, high s/n, low mass, low power solution
 - applicable to both eRHIC and JLEIC

Central detector: overview

- Asymmetric IP location within solenoid and different endcaps
 - Maximizes solid angle for electron endcap
 - More space for tracking and ID of high-momentum forward-going hadrons
- Makes full use of 50 mrad crossing angle and 2 Tm dipole



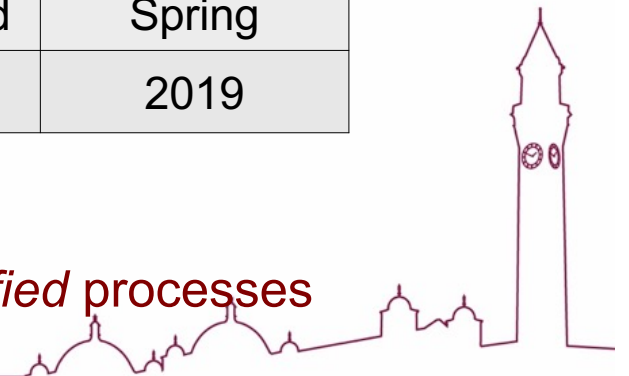
Pawel Nadel-Turonski

WP1: Sensor development

- Aim: to demonstrate *high spatial resolution* in a *fully depleted* sensor
 - Advantage of depletion = charge collection by drift
 - ➔ larger Q, faster collection, smaller cluster multiplicity
 - ➔ plus improved radiation hardness (not essential for the EIC)
- Technology development
 - Exploiting our involvement in other projects (not EIC specific)

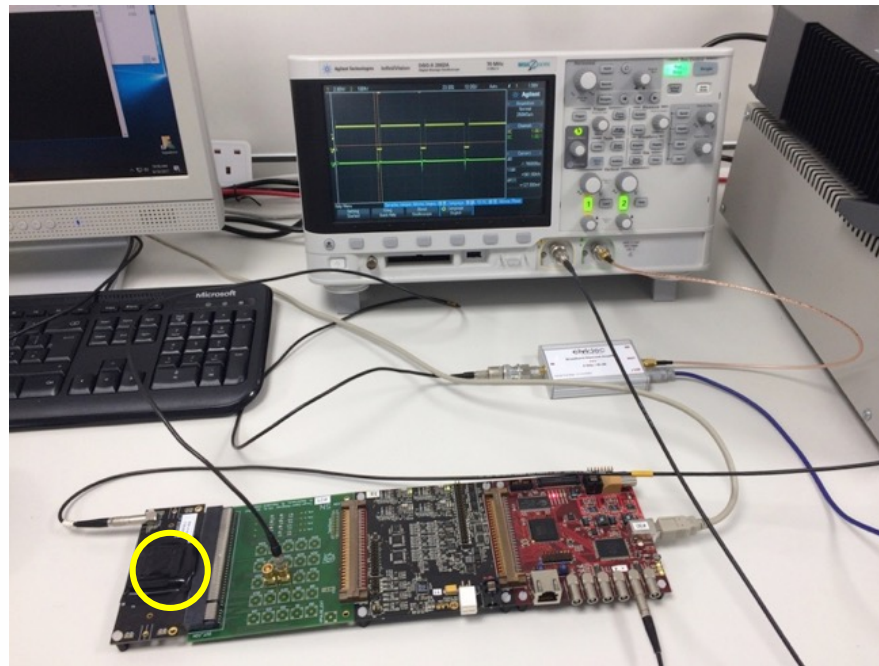
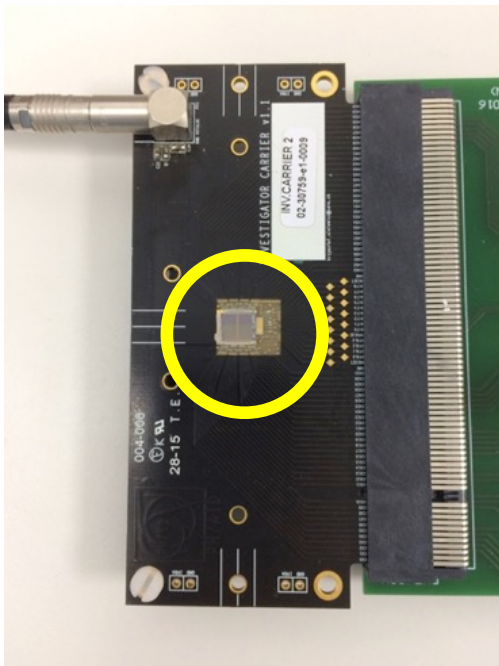
Project	Pixel sizes	Electrode	Process	Availability
CERN-TJ	20 x 20 μm^2 to 50 x 50 μm^2	Single small	TJ standard TJ modified	Now
DECAL	50 x 50 μm^2	Multiple	TJ standard TJ modified	Now Spring
RD50	$\geq 20 \times 20 \mu\text{m}^2$	Single large	LFoundry	2019

- Current focus is the CERN-TJ investigator chip
- Permits a comparison between *standard* and *modified* processes



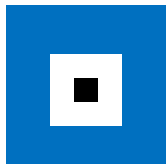
WP1: Sensor development

- CERN-TJ investigator chip now available for testing in Birmingham
 - Designed to study charge collection properties and detection efficiency
 - More than 100 pixel matrices (8 x 8 pixels)
 - Range of pixel sizes relevant to both EIC barrel and disks
 - 20 x 20 μm^2 to 50 x 50 μm^2 pixels
 - Simple follower-based (analogue-only) readout

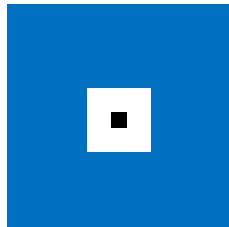


WP1: Sensor development

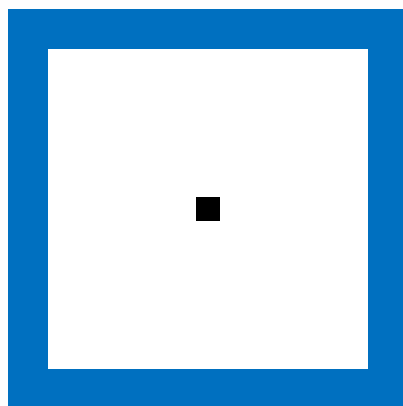
■ CERN-TJ Investigator: first look



Pixel: $20 \times 20 \mu\text{m}^2$
Electrode: $3 \times 3 \mu\text{m}^2$
Electrode spacing: $3 \mu\text{m}$



Pixel: $28 \times 28 \mu\text{m}^2$
Electrode: $2 \times 2 \mu\text{m}^2$
Electrode spacing: $3 \mu\text{m}$



Pixel: $50 \times 50 \mu\text{m}^2$
Electrode: $3 \times 3 \mu\text{m}^2$
Electrode spacing: $18.5 \mu\text{m}$

Available pixel matrices

0-35:	$20 \times 20 \mu\text{m}^2$
36-57:	$22 \times 22 \mu\text{m}^2$
58-67:	$25 \times 25 \mu\text{m}^2$
68-103:	$28 \times 28 \mu\text{m}^2$
104-111:	$30 \times 30 \mu\text{m}^2$
112-123:	$40 \times 40 \mu\text{m}^2$
124-133:	$50 \times 50 \mu\text{m}^2$

Electrode sizes

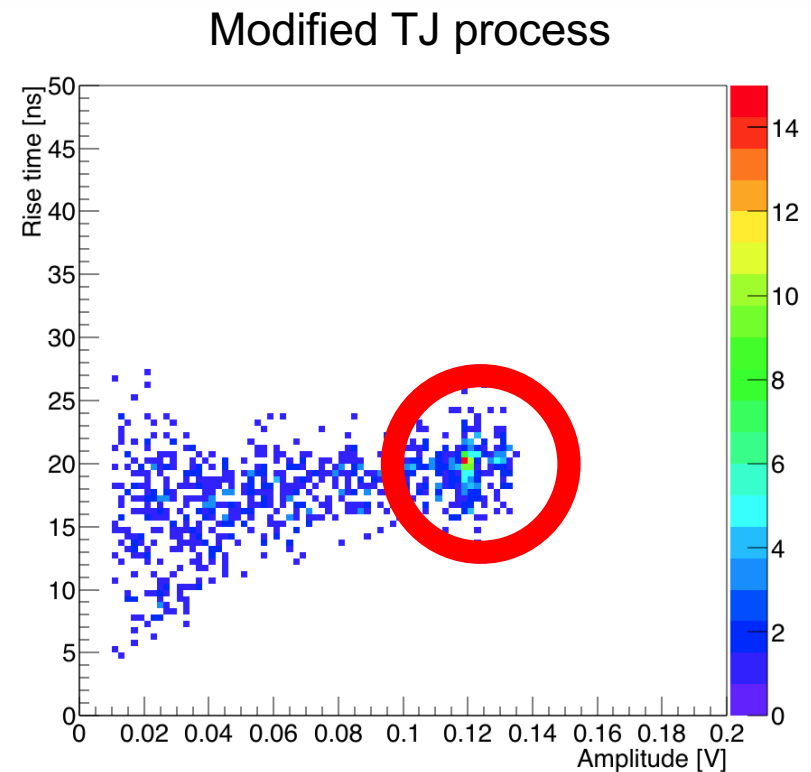
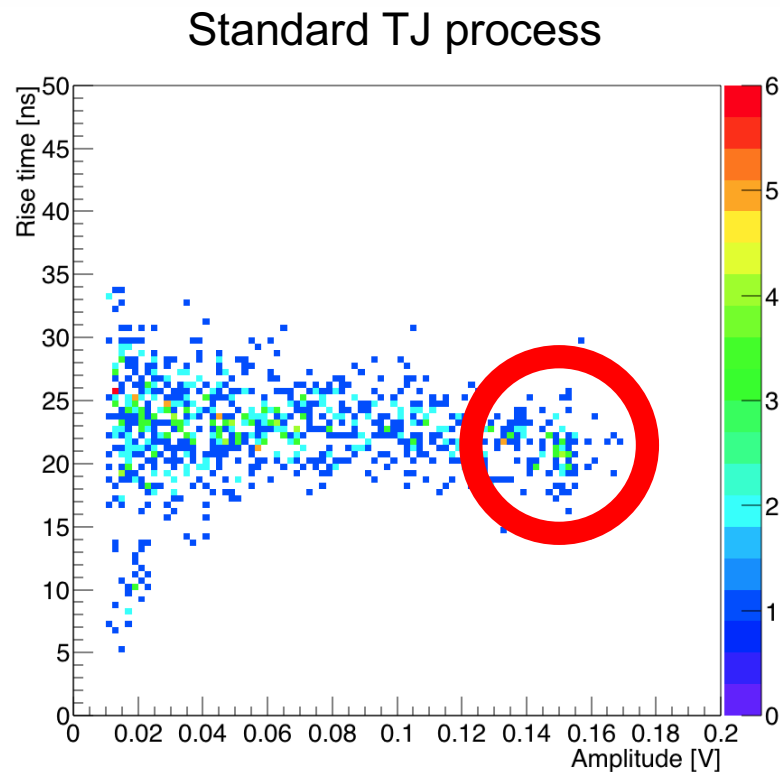
$1\text{-}5 \mu\text{m}^2$

Electrode spacing

$1\text{-}5 \mu\text{m}$ typically
(except $50 \times 50 \mu\text{m}^2$ pixels)

WP1: Sensor development

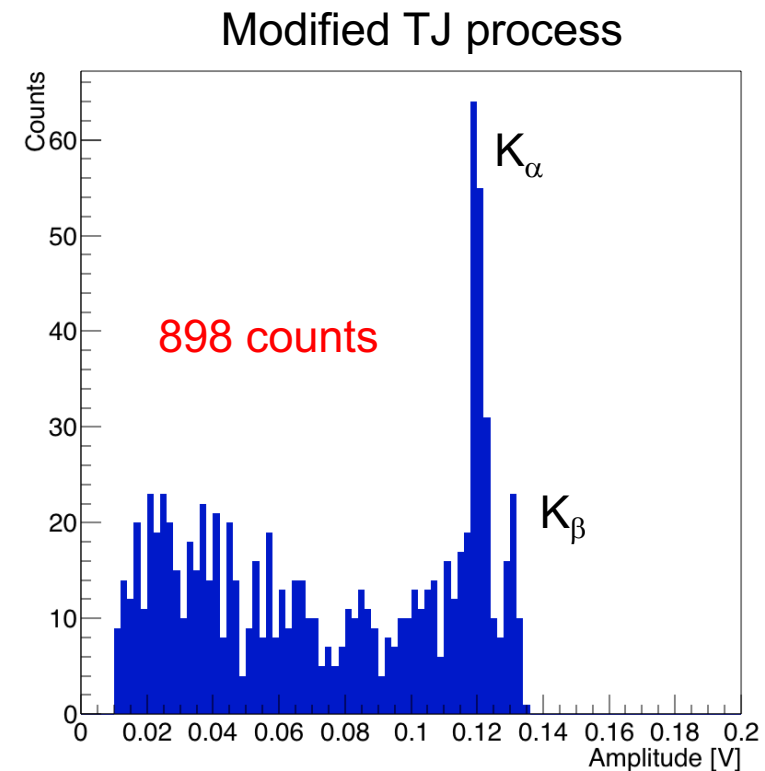
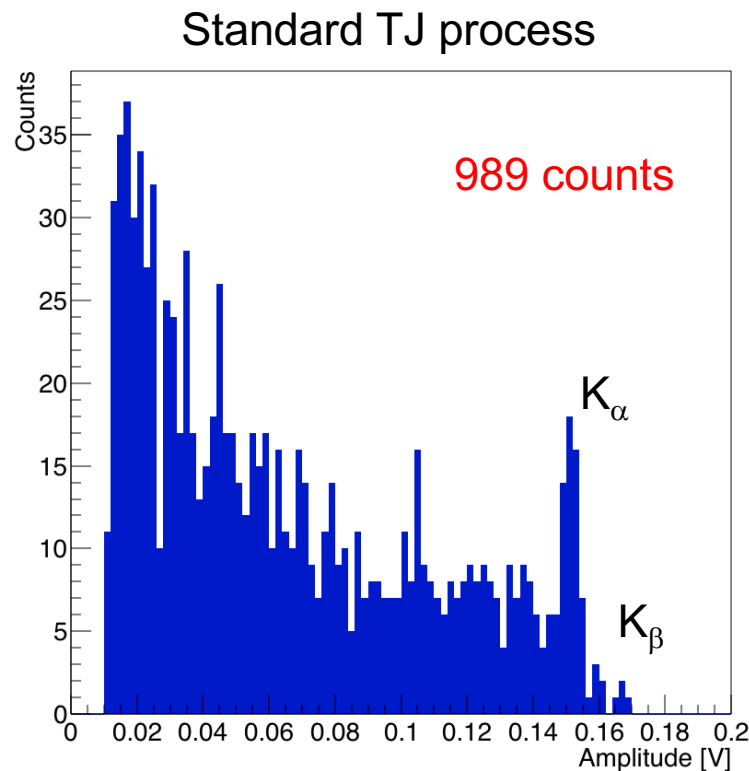
- Comparison of TJ *standard* and *modified* processes
 - 28 x 28 μm^2 pixels, tests with ^{55}Fe source



- More large amplitude signals with the modified process
 - Due to more complete charge collection

WP1: Sensor development

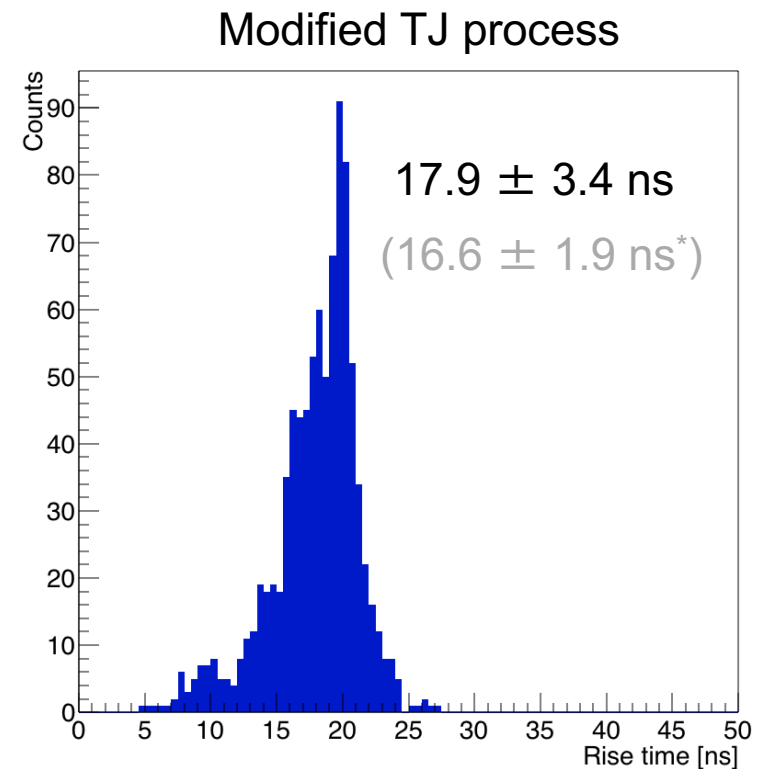
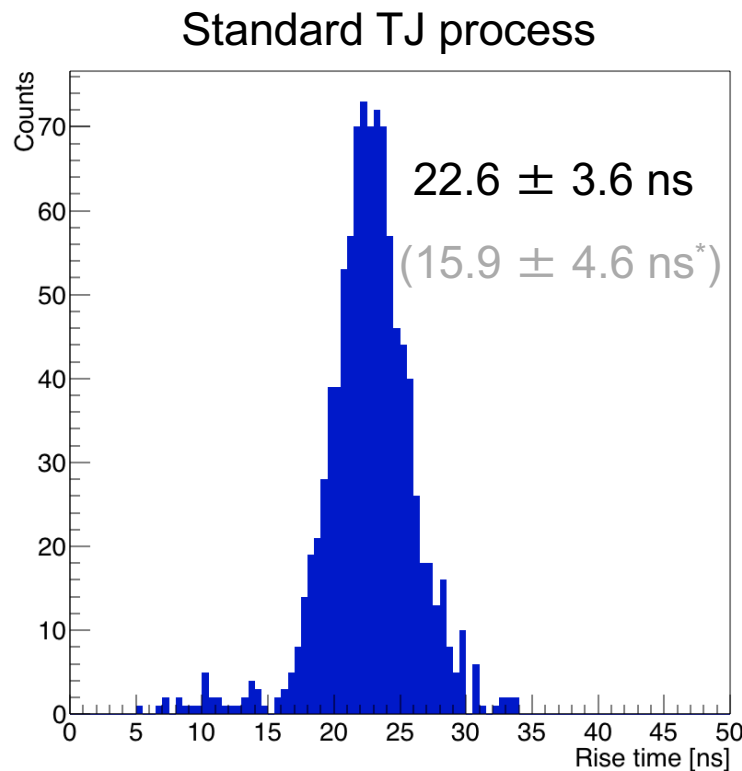
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- More large amplitude signals with the modified process
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WP1: Sensor development

- Comparison of TJ *standard* and *modified* processes
 - 28 x 28 μm^2 pixels, tests with ^{55}Fe source



- Modest improvement in signal rise time for the modified process
- Note: published studies* ~ 16 ns (50 x 50 μm^2 pixels)

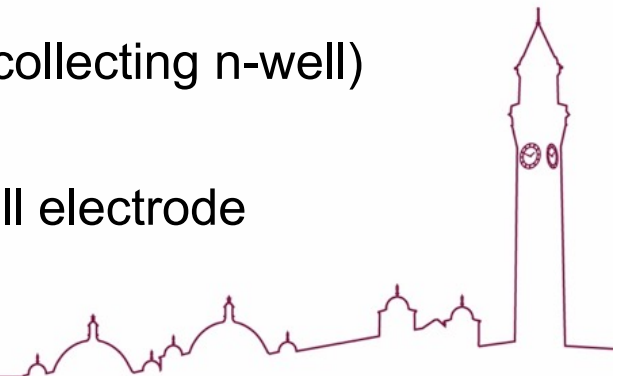
* H. Pernegger et al., 2017 JINST 12 P06008

WP1: Sensor development

- Update on other developments
 1. **DECAL prototype in TowerJazz standard process**
 - Part of a separate Digital ECal (DECAL) project (UK funded PRD)
 - Consists of larger pixels ($50 \times 50 \mu\text{m}^2$) and four small collection electrodes to match requirements of DECAL project
 - Undergoing initial tests; readout being developed
 2. **DECAL test structures in TowerJazz modified process**
 - Multi-Project Wafer submission with CERN in July
 - Consists of passive versions of the DECAL prototype pixels
 3. **RD50 LFoundry submission expected by end of 2018**
 - Matrices with **improved time resolution** (in-pixel TOA and TDC)
 - Test structures with pixels down to $20 \times 20 \mu\text{m}^2$
 - But, large electrode (electronics sits within the collecting n-well)

All options are useful for evaluation purposes ...

Expect larger Q, but also larger C than single small electrode



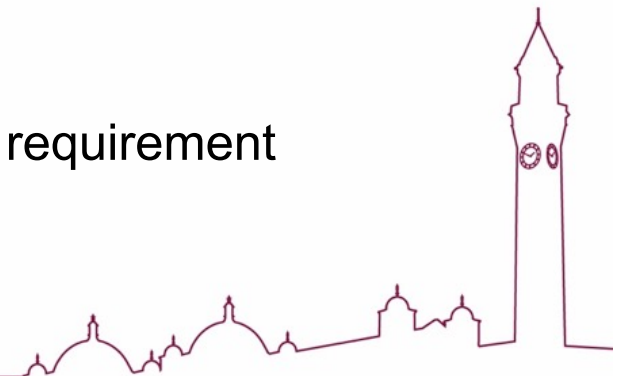
WP2: Simulations

- Update on manpower
 - EIC (FY17) R&D funds supported a postdoc for 5.5 months
 - Post filled by Dr. Sam Bailey; left to take up a new job in the summer
 - A new UoB-funded PhD student (Håkan Wennlöf) started in October
 - Håkan performed all the initial tests of the CERN-TJ investigator
 - He has now started to revisit the simulations work started by Sam
- Focus on simulations in EicRoot software framework
 - Studied pions (kaons and protons) from 500 MeV/c to 10 GeV/c
 - Various barrel configurations plus default TPC specification
 - 4-layer barrel, default geometry, 20-40 μm pixels
 - 3, 4 and 5-layer barrels, 30 μm pixels
- Plan for the next 6 months
 - Optimise the number and radial position of the layers
 - Mainly concerned with pointing resolution at low p_T
 - Consider option of having an outermost layer with lower intrinsic resolution (larger pixels) but added timing capability



eRD18: Project summary

- WP1: Sensor development
 - Started characterisation of CERN-TJ investigator
 - Demonstrated improved charge collection with the modified process
 - Currently investigating amplifier behaviour with vendor (CIVIDEC) to understand the dependence of rise time on signal amplitude
 - Plan to continue characterisation studies with a new amplifier
- WP2: Simulations
 - Restarting simulation studies
 - Optimise the number and radial position of the layers
 - Aim for pointing resolution $\sim 30 \mu\text{m}$ at 1 GeV/c (cf. $D^0 c\tau \approx 120 \mu\text{m}$)
 - Consider option of a tracking layer with added timing capability
 - Outer layer with larger pixels
 - Optimise pixel size with outer tracker
 - Consult with a chip designer to estimate power requirement

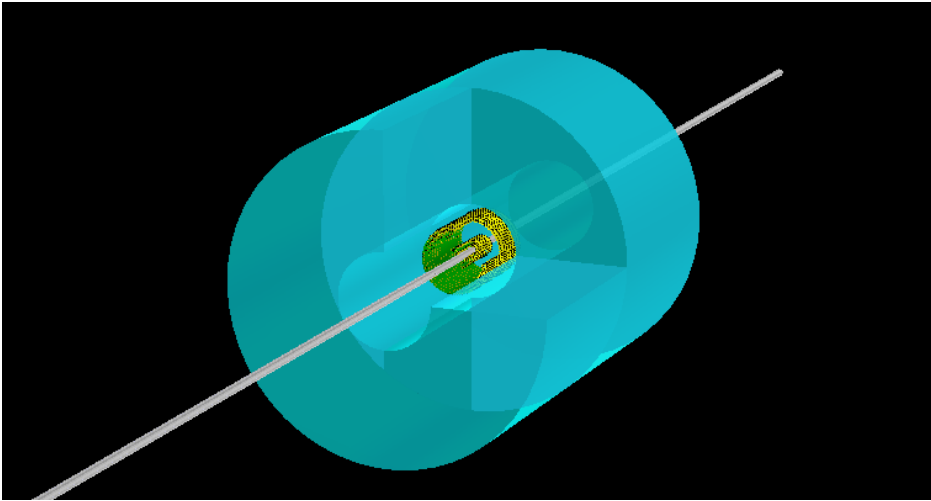


Backup Slides



WP2: Simulations

- Geometry: TPC + VST + beam pipe + magnetic field ($B = 1.5$ T)



TPC parameters

Inner radius = 20 cm

Outer radius = 80 cm

250 μm position resolution

VST parameters

Layer #1 radius = 2.3 cm

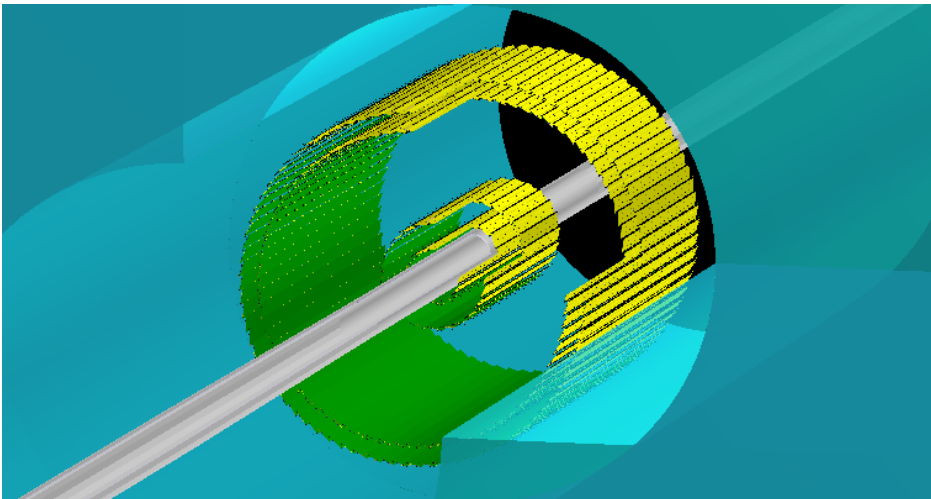
Layer #2 radius = 4.6 cm

Layer #3 radius = 14 cm

Layer #5 radius = 16 cm

30 x 30 μm pixels

0.3% X_0 per layer



Beam pipe parameters

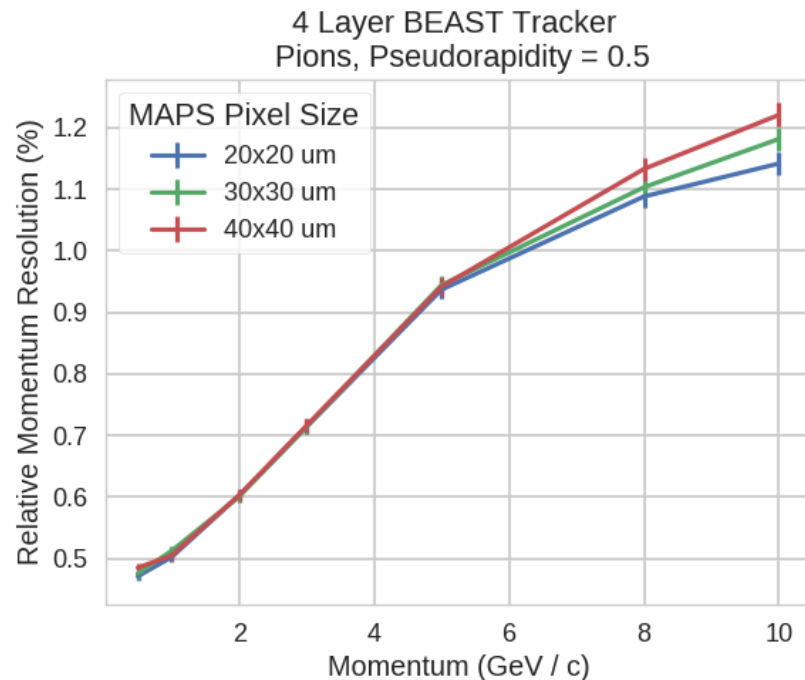
Material = beryllium

Outer radius = 1.8 cm

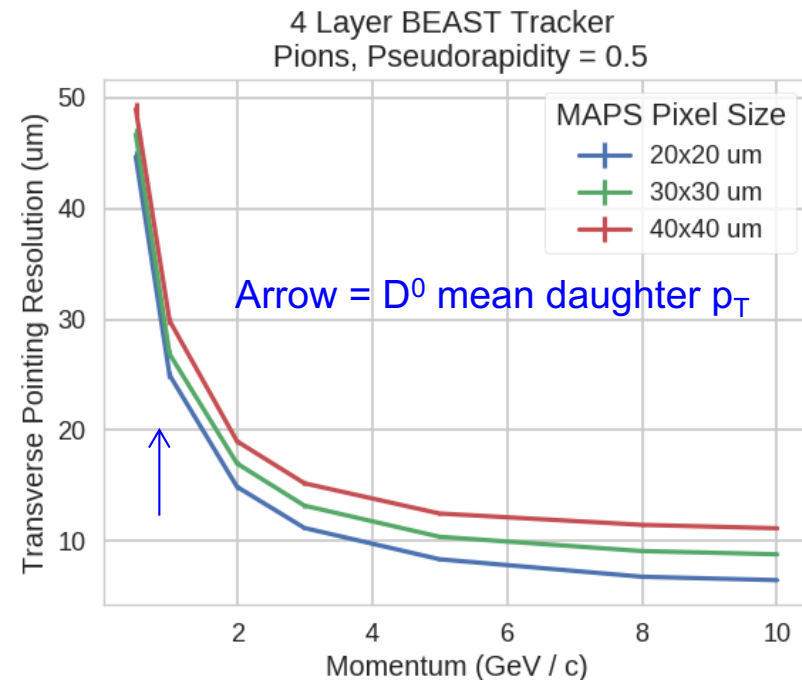
Thickness = 0.8 mm

WP2: Simulations

- Results: pions; $\eta = 0.5$; 3 pixel sizes: 20 μm , 30 μm and 40 μm



Relative momentum resolution (%)
versus momentum

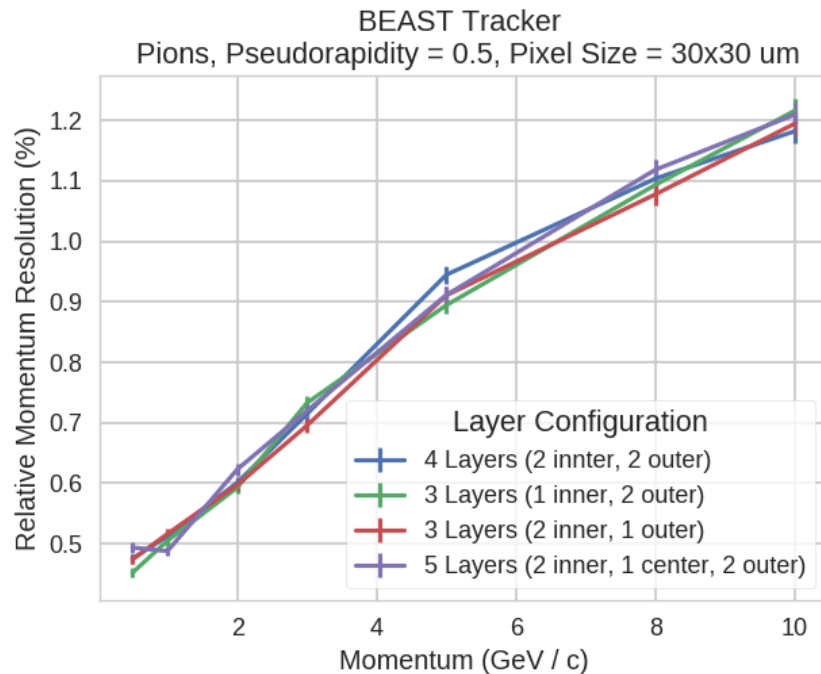


Impact parameter resolution (μm)
in transverse (r - ϕ) plane
versus momentum

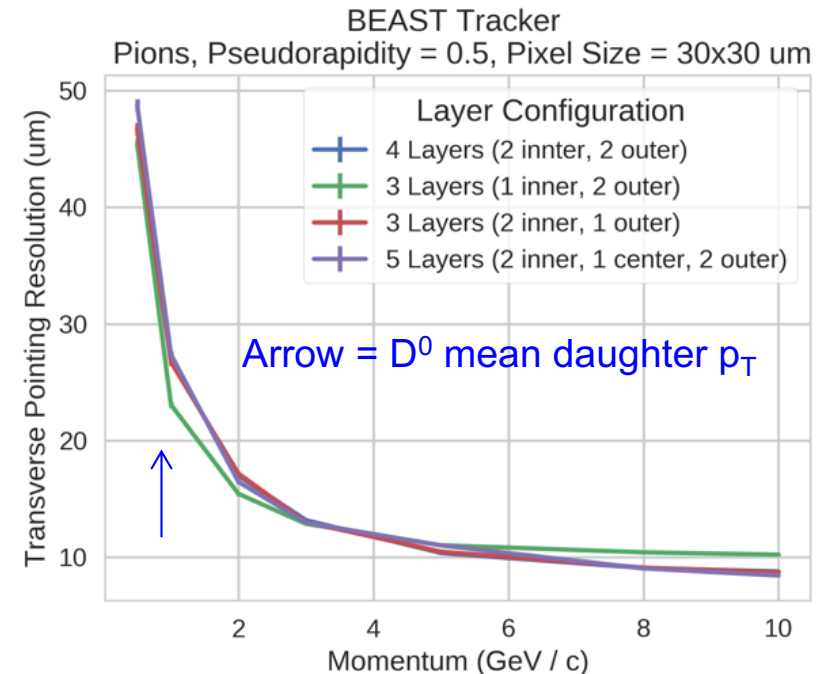
- Modest improvement in impact parameter resolution for all p_T
 - Dominated by resolution of innermost layer

WP2: Simulations

- Results: pions; $\eta = 0.5$; pixel size = $30\ \mu\text{m}$; 3, 4 and 5 layers



Relative momentum resolution (%)
versus momentum

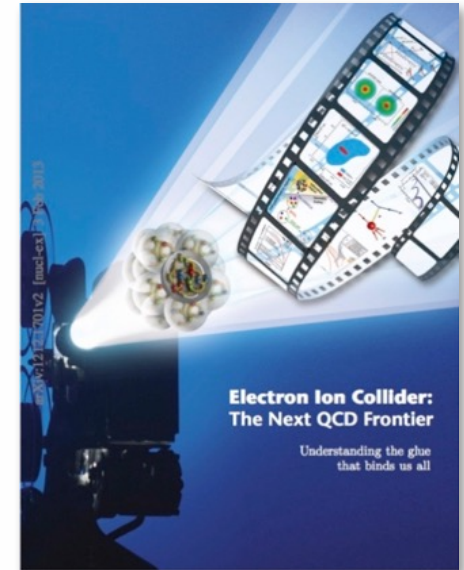


Impact parameter resolution (μm)
in transverse (r - ϕ) plane
versus momentum

- Little sensitivity to the number of layers
 - Slightly better impact parameter resolution with one inner layer

Charm observables in the EIC White Paper

- Leading order charm production process is γg fusion
- Provides sensitivity to:
 - I. The gluon contribution to spin of the nucleon
 - Charm sensitive to Δg in e-p scattering
 - II. Physics of high gluon densities and low-x in nuclei
 - Measurement of F_2^{charm} sensitive to nuclear gluon density in e-A
 - III. Hadronisation and energy loss in cold nuclear matter
 - Nuclear modification and quark mass dependence
- A future EIC promises unprecedented precision in charm (and beauty)
 - Reconstruction challenging due to short decay lengths $\sim 100 \mu\text{m}$
 - Likely to place strongest constraints on the tracker design
 - Potential importance of low- p_T (standalone) tracking



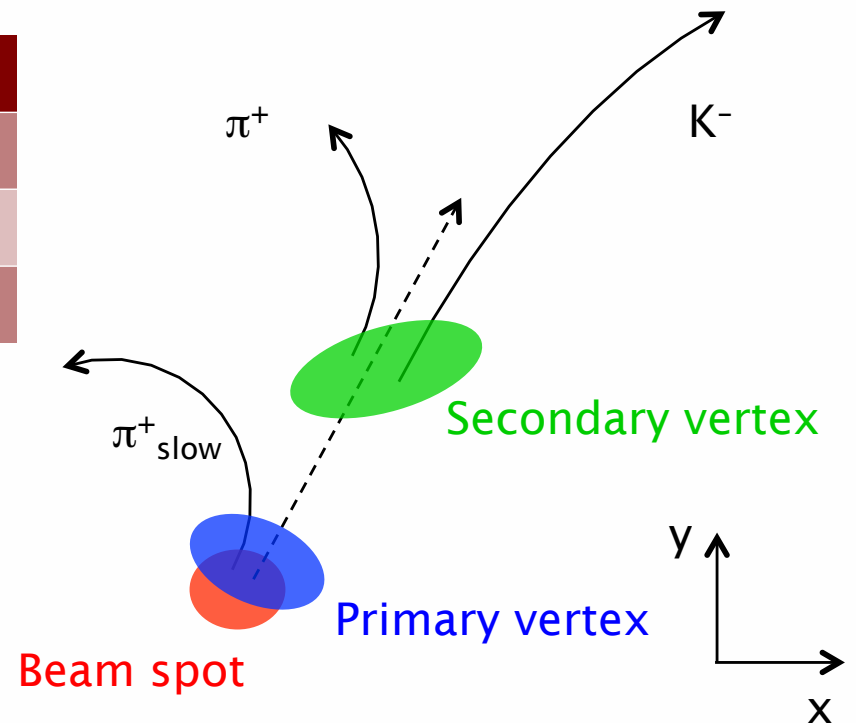
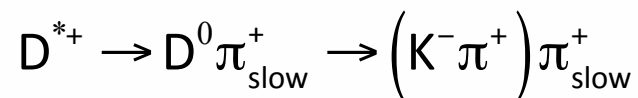
A. Accardi et al.,
Eur. Phys. J. A (2016) 52:268

Open charm reconstruction

- Signature is displaced (secondary) decay vertex

Particle	Decay	Branching	$c\tau$ [μm]
D^0	$K^-\pi^+$	3.9%	123
D^+	$K^-\pi^+\pi^+$	9.5%	311
D^{*+}	$D^0\pi^+_{\text{slow}}$	67.7%	

Example:



- Requires excellent impact parameter resolution in r - ϕ and z
 - Dominated by position and resolution of innermost tracking layer
 - Close as possible to beam pipe (caution: radiation environment)
 - Highest possible spatial resolution (small pixels)